



PLACE-N-BOND™ PRODUCT DATA SHEET

RP-113184 Pick and Place Underfilm *Multi-Purpose*

FEATURES

- Enhances adhesion for multi-surface bonding
- Reduces cost by combining pick and place plus soldering in one heating pass (no dispensing)
- No capital expense or equipment required
- Compatible with existing lead and Pb-free materials and reflow profiles
- Air or nitrogen reflow compatible
- Requires no pre-baking of boards
- RoHS compatible
- AOI easy recognition
- Underfilm system established in 2005
- Patented in USA and other countries



APPLICATION

- Pick and Place Underfilm technology was developed to reduce solder joint fatigue failures caused from drop and shock associated with brittle lead free solder joints and reduced joint size due to BGA miniaturization
- Simplified application utilizing existing tape and reel feeders plus high-volume pick and place equipment on a current SMT assembly line
- Underfilm does not interact with solder or flux

INTRODUCTION

- Residue and solvent free, requires no post cleaning
- Migration free, will not interfere with solder or flux
- Micro precision technology allows for other SMT components to be placed in close proximity

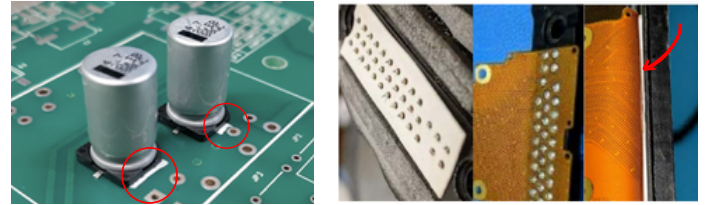
RELIABILITY

- Underfilm offers excellent adhesion to many devices
- Edge weighted 6 foot drop test* results show a minimum of 10x improvement in solder joint reliability over BGA alone. 50x improvement has been obtained

MANUFACTURING

- No equipment purchase required
- No extra floor space required
- No fumes because no dispensing
- No equipment to maintain or needles to clog
- No additional cure cycle
- No uncured cleaning required
- No pre-bake required
- 100% material utilization because no dispense

*similar to other published BGA drop test reliability studies

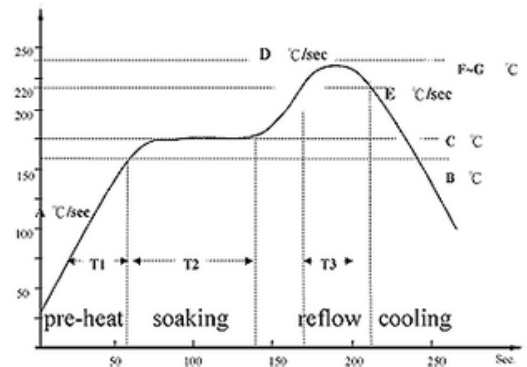


PACKAGING

- Supplied on reel per EIA 481 carrier tape
- Utilization of precision carrier tape, cover tape and standard reels
- Static shielding bag and sealed, MSL 1

PROCESS RECOMMENDATIONS

- Screen print solder paste, pick and place Underfilm, pick and place BGA, reflow
- No dehydration bake required / no clean
- Standard Pb-free reflow profiles can be used



REWORK

- Underfilm is 100% reworkable

STORAGE AND HANDLING

- No special storage or handling required
- Long shelf life

MECHANICAL

Hardness Shore A	82A
Tensile Modulus	20 mPa
Vicat Softening Point	77 C
Specific Gravity	1.00g/cc
CTE	21 10 ⁻⁵ /°C

SAFETY

- Underfilm is a benign, non-toxic material under a typical reflow profile

